## PATENT APPLICATION

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of Docket No: Q84452 Michel PUECH Group Art Unit: 1763 Appln. No.: 10/516,455 Confirmation No.: 2876 Examiner: Allan W. OLSEN Filed: December 3, 2004 METHOD AND DEVICE FOR SUBSTRATE ETCHING WITH VERY HIGH POWER For: INDUCTIVELY COUPLED PLASMA AMENDMENT UNDER 37 C.F.R. § 1.111 MAIL STOP AMENDMENT Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 Sir: In response to the Office Action dated August 15, 2007, please amend the aboveidentified application as follows on the accompanying pages. **TABLE OF CONTENTS** AMENDMENTS TO THE CLAIMS......2 REMARKS......4